



Material Content Data Sheet



Sales Product Name				BSC090N03MS G		Issued		19. January 2018	
MA#				MA001123616					
Package				PG-TDSON-8-14		Weight*		118.59 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.743	0.63	0.63	6269	6269	
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82		
	non noble metal	zinc	7440-66-6	0.039	0.03		328		
	non noble metal	iron	7439-89-6	0.778	0.66		6561		
wire	non noble metal	copper	7440-50-8	31.590	26.64	27.34	266390	273361	
	non noble metal	copper	7440-50-8	0.058	0.05	0.05	486	486	
	encapsulation	organic material	carbon black	1333-86-4	0.241	0.20		2036	
encapsulation	plastics	epoxy resin	-	7.484	6.31		63113		
	inorganic material	silicondioxide	60676-86-0	40.560	34.21	40.72	342032	407181	
	leadfinish	non noble metal	tin	7440-31-5	1.243	1.05	1.05	10478	10478
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	316	316	
solder	noble metal	silver	7440-22-4	0.027	0.02		225		
	non noble metal	tin	7440-31-5	0.021	0.02		180		
	non noble metal	lead	7439-92-1	1.019	0.86	0.90	8597	9002	
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	zinc	7440-66-6	0.021	0.02		180		
	non noble metal	iron	7439-89-6	0.428	0.36		3605		
heat sink CLIP	non noble metal	copper	7440-50-8	17.360	14.64	15.02	146392	150222	
	non noble metal	iron	7439-89-6	0.017	0.01		143		
	inorganic material	phosphorus	7723-14-0	0.005	0.00		43		
*deviation	non noble metal	copper	7440-50-8	16.898	14.25	14.26	142499	142685	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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